

XP-002216248

AN - 1993-269507 [34]

A - [001] 017 03- 032 034 040 041 046 047 066 067 139 231 27& 354 359 38&
387 397 402 408 409 428 431 434 436 456 473 551 560 562 597 600 604
606 609 617 699

AP - JP19920024637 19920113

CPY - SHOE

DC - A81 F09

FS - CPI

IC - B29C67/14 ; B29K105/12 ; B29L31/10

KS - 0009 0218 0229 0241 0789 1276 2017 2020 2195 2198 2371 2386 2413 2424
2430 2459 2493 2504 2624 2659 2665 2682 2836 2844 3155

MC - A11-B09B A11-C02C A12-A04B A12-R06 F05-A07

PA - (SHOE) SHOEI KAGAKU KOGYO KK

PN - JP5185524 A 19930727 DW199334 B29C67/14 004pp

PR - JP19920024637 19920113

XA - C1993-120071

XIC - B29C-067/14 ; B29K-105/12 ; B29L-031/10

AB - J05185524 In the process cellulose fibres are coated with an aq.
adhesive, mixed and dried and cured by h.f. dielectric heating to be
moulded.

- Pref. the h.f. dielectric heating is applied together with heating
with a hot plate, for drying and curing. Pref. the aq. adhesive is a
vinyl resin emulsion, a synthetic rubber latex, and/or an amino resin.
The solid content of the aq. adhesive is pref. 3-50 pts.wt. based on
the absolute dry wt. of the cellulose type fibres.

- USE/ADVANTAGE - As sound-proofing, thermal insulative, shock
absorptive material, etc.. The heating for drying and moulding is
performed for a short time.

- In an example, cellulose fibres 100 pts.wt. are opened and mixed with
an EVA copolymer emulsion adhesive (solid content 59%) 30 pts.wt. by
spraying, and is placed between electrodes in a wood mould. With a
h.f. oscillator, the mixt. is heated at 4000 V, 0.5A for 2
minutes.(Dwg.0/0)

IW - CELLULOSE@ FIBREBOARD PRODUCE BUILD MATERIAL COATING CELLULOSE@ FIBRE
AQUEOUS ADHESIVE DRY CURE HF DIELECTRIC HEAT

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AQUEOUS ADHESIVE DRY CURE HF DIELECTRIC HEAT

NC - 001

OPD - 1992-01-13

ORD - 1993-07-27

PAW - (SHOE) SHOEI KAGAKU KOGYO KK

TI - Cellulose@ fibreboard prodn., used for building material - by coating
cellulose@ fibres with aq. adhesive, drying and curing by HF
dielectric heating